

Attorney's Docket No.: 042390.P3955D

Patent

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Pre Amended
S. Bryce
2/4/00

In Re Application of:

Ebrahim Andideh et al.

Serial No: Not yet assigned

Filed: November 8, 1999

For: Polish Pad with Non-Uniform Groove
Depth to Improve Wafer Polish Rate
Uniformity

Examiner: Not yet assigned

Art Unit: Not yet assigned

Assistant Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to an examination of the above-identified application, and prior to calculating the filing fee of the enclosed divisional application, please enter the following amendments.

IN THE CLAIMS:

✓ Please cancel claims 1-26, without prejudice as drawn to a non-elected invention.

Claims 27-53 remain in the application and are drawn to an apparatus, classified in class 156, subclass 345.

REMARKS

Reconsideration of this application in view of the foregoing amendments and the following remarks is respectfully requested.

Applicants respectfully requests consideration of this application in view of the foregoing amendments. This divisional application is being filed in response to an election requirement mailed on April 23, 1999, for parent case serial no. 08/997,293 filed on

653071-2695460